

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPI80N08S4-06	**Issued**	24. February 2022
MA#	MA005708897		
Package	PG-TO262-3-1	**Weight***	1574.66 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.425	0.28	0.28	2810	2810
leadframe	inorganic material	phosphorus	7723-14-0	0.255	0.02		162	
	non noble metal	iron	7439-89-6	0.851	0.05		540	
	non noble metal	copper	7440-50-8	849.682	53.97	54.04	539595	540297
wire	non noble metal	aluminium	7429-90-5	7.229	0.46	0.46	4591	4591
encapsulation	inorganic material	zincoxide	1314-13-2	5.870	0.37		3728	
	miscellaneous	miscellaneous	-	23.479	1.49		14911	
	plastics	epoxy resin	-	88.048	5.59		55915	
	inorganic material	silicondioxide	60676-86-0	469.589	29.82	37.27	298216	372770
leadfinish	non noble metal	tin	7440-31-5	15.198	0.97	0.97	9651	9651
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	145	146
solder	non noble metal	tin	7440-31-5	0.069			44	
	noble metal	silver	7440-22-4	0.087	0.01		55	
	non noble metal	lead	7439-92-1	3.305	0.21	0.22	2099	2198
heatspreader	inorganic material	phosphorus	7723-14-0	0.032			20	
	non noble metal	iron	7439-89-6	0.106	0.01		68	
	non noble metal	copper	7440-50-8	106.210	6.74	6.75	67449	67537
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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